

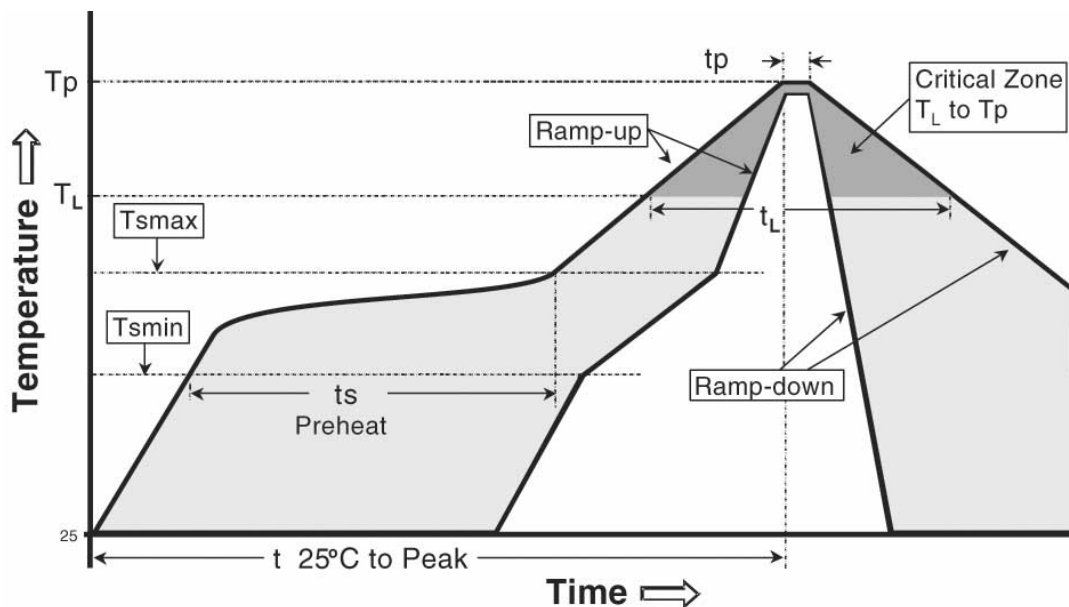
I. SM200 Package (Surface Mount Substrate)

ASI Semiconductor recommends using the solder reflow criteria as specified in JEDEC Standard J-STD-020D.1 shown below.

Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average ramp-up rate (T _{smax} to T _p)	3° C/second max.	3° C/second max.
Preheat		
- Temperature Min (T _{smin})	100 °C	150 °C
- Temperature Max (T _{smax})	150 °C	200 °C
- Time (T _{smin} to T _{smax}) (t _s)	60-120 seconds	60-180 seconds
Time maintained above:		
- Temperature (T _L)	183 °C	217 °C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature (T _p)	See Table 4.1	See Table 4.2
Time within 5°C of actual Peak Temperature (t _p) ²	10-30 seconds	20-40 seconds
Ramp-down Rate	6 °C/second max.	6 °C/second max.
Time 25°C to Peak Temperature	6 minutes max.	8 minutes max.

Note 1: All temperatures refer to topside of the package, measured on the package body surface.

Note 2: Time within 5 °C of actual peak temperature (t_p) specified for the reflow profiles is a “supplier” minimum and “user” maximum.



ASI Semiconductor also recommends consulting the solder paste manufacturer for the proper ramp and soak rates for their particular products.